

Initial Product/Process Change Notification Document #:IPCN25232X Issue Date:15 Feb 2023

wire material change for SC88A and TSOP5 packages assembled in onsemi, Seremban, M NCS333A family.           Proposed First Ship date:         30 Sep 2023 or earlier if approved by customer           Contact Information:         Contact your local onsemi Sales Office or CheePan, Eoo®Densemi.com           PCN Samples Contact:         Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification initial PCN or this change. Samples delivery timing will be subject to request date, sample quantity and special cust packing/label requirements.           Type of Notification:         This is an initial PCN or this change. Samples delivery timing will be subject to request date, sample quantity and special cust packing/label requirements.           Type of Notification:         This is an initial PCN or this change. Samples delivery timing will be subject to request date, sample quantity and special cust packing/label requirements.           Type of Notification:         This is an initial PCN or this Cano in the preliminary reliability qualificati The completed qualification and characterization data will be included in the Final Product/Process Change Notification (PCN). This IPCN notification will be followed by a Product/Process Change Notification (PCN). This IPCN notification of change. In case of questions, contact +PCN Support@ensemi.com>           Marking of Parts/ Traceability of Change.         The affected products will be identified with date code and custom source           Change Sub-Category(s):         Material Change, Manufacturing Site Addition           Sites Affected:         None							
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	Fab Site	onsemi Gresham, Ore	egon, USA	onsemi Aizu, Aizuwakamatsu, Japan, onsemi Gresham, Oregon, USA			
	LeadFrame – TSOP5	Ag Stripe		roughened ppf			

CRM1084P

0.8mil Au

Die Attach – TSOP5

Bond Wire

Ablestick 8006NS

0.8mil AuFlash PCC

# onsemi

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QV DEVICE NAME: NCS333ASQ3T2G RMS: S89456 PACKAGE: SC-88A-5							
Test	Specification	Condition	Interval				
High Temperature Operating Life	JESD22-A108	Ta=125°C, 100 % max rated Vcc	1008 hrs				
Early Life Failure Rate	JESD22-A108	Ta=125°C, 100 % max rated Vcc	48 hrs				
High Temperature Storage Life	JESD22-A103	Ta= 150°C	1008 hrs				
Highly Accelerated Stress Test	J-STD-020, JESD22-A110	130°C/85%RH/18.8psig, biased	96 hrs				
Unbiased Highly Accelerated Stress Test	J-STD-020, JESD22-A118	130°C/85%RH/18.8psig	96 hrs				
Temperature Cycling	J-STD-020, JESD22-A104	-65°C to +150C	1000 cyc				
ESD-HBM	JS-001-2017	2000V	-				
ESD-CDM	JS-002-2018	1000V	-				
LU Class II	JESD-78	100mA					
Electrical Distribution / Thermal Characterization	onsemi DataSheet	Test @ Cold & Room & Hot Cpk ≥ 1.67	-				

Estimated date for qualification completion: 30 June 2023

#### List of Affected Parts:

**Note:** Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

Part Number	Qualification Vehicle	
NCS333ASN2T1G	NCS333ASQ3T2G	
NCS333ASQ3T2G	NCS333ASQ3T2G	

# Appendix A: Changed Products

### DIKG: DIGI-KEY

Product	Customer Part Number	Qualification Vehicle	New Part Number	Replacement Supplier
NCS333ASN2T1G		NCS333ASQ3T2G	NA	
NCS333ASQ3T2G		NCS333ASQ3T2G	NA	